This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) A wafer engine for moving semiconductor workpieces, comprising:

a linear drive assembly having a carriage, said linear drive assembly for moving said carriage between a first <u>position</u> and <u>a</u> second position along a first linear path, said first linear path defining an x-axis;

a base-mounted to said carriage;

a support column having a first end and a second end;

- a rotational drive housed within said base mounted to said carriage and affixed to said first end of said having a support column that extends out of said base, said rotational drive adapted to rotate said support column about a longitudinal central axis of said support column, said longitudinal central axis defining a theta axis;
- a z-axis drive housing having a base portion and an elongated body, said base portion mounted to said second end of said support column such that said rotational drive rotates said z-axis drive housing about said theta axis;
- a z-axis drive assembly housed substantially within said elongated body, said z-axis drive assembly adapted to move between a first <u>position</u> and <u>a</u> second position along a second linear path, said second linear path defining a z-axis <u>that is offset from said theta axis</u>; and
- a radial drive housing mounted to said z-axis drive assembly, said radial drive housing enclosing a radial drive assembly adapted to move an end effector between a first position and second position along a third linear path, said third linear path defining a radial axis.
- 2. (Previously Cancelled)
- 3. (Currently Amended) The wafer engine as recited in claim $\underline{1}$ 2, wherein said rotational drive simultaneously rotates said z-axis drive housing and said radial drive housing about said theta axis.